

## GENERAL DESCRIPTION

The EM23C1000 series high performance Read Only Memory is organized as 131,072 words by 8 bits. It is designed to be compatible with all microprocessor and similar applications where high performance large bit storage and simple interface are important design considerations.

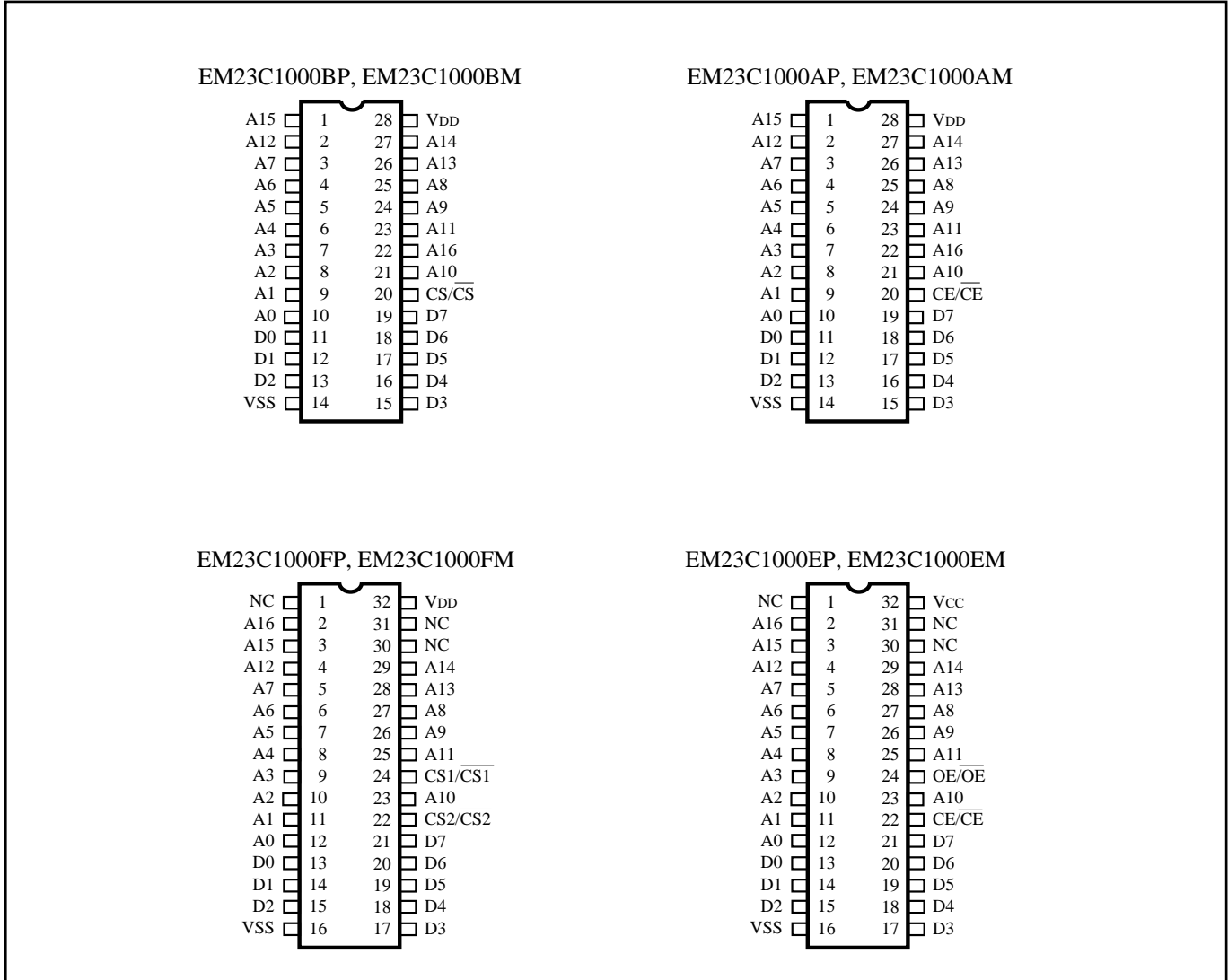
The EM23C1000 series have two type. The one is offer the simplest operation (no power down). Its programmable chip selects allow up to four 1M ROMs to be Wired-OR without external decoding.

The other one has the automatic power down feature. The power down capability is controlled by the Chip Enable ( $\overline{CE}/\overline{CE}$ ) input. When  $\overline{CE}$  goes to high or  $\overline{CE}$  goes low, the device will automatically goes to power down mode and remains in a low power standby mode as long as  $\overline{CE}$  remains high. This unique feature provides system level power savings as much as 90%. An additional feature of this type is the Output Enable ( $\overline{OE}/\overline{OE}$ ) function. This eliminates bus connection in multiple bus microprocessor systems.

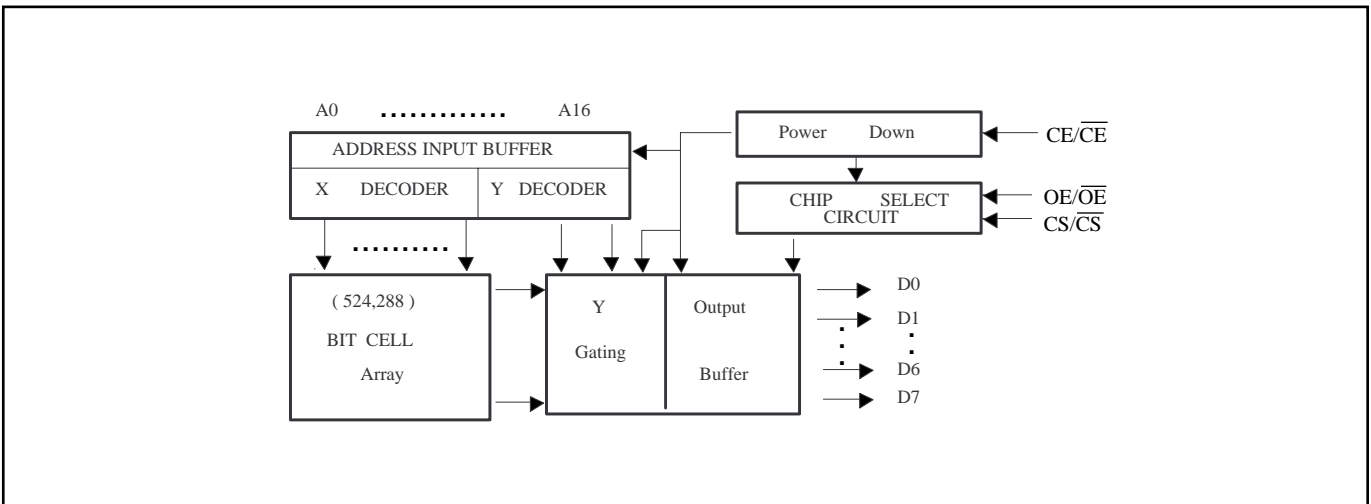
## FEATURES

- 131,072 x 8 bit organization
- Access time 150 ns (max.) at  $4.5V \leq V_{CC} \leq 5.5V$
- Low-power consumption:
  - Operating: 193 mW (max.)
  - Standby: 165  $\mu$ W (max.)
- Fully-static operation
- Three-state outputs
- Completely TTL compatible.
- EM23C1000BP, EM23C1000FP.  
EM23C1000BM, EM23C1000FM.
  - Non power down version.
  - Two programmable chip selects ( $\overline{CS}/\overline{CS}$ ).
- EM23C1000AP, EM23C1000EP.  
EM23C1000AM, EM23C1000EM.
  - Automatic power down ( $\overline{CE}/\overline{CE}$ ).
  - Output Enable function ( $\overline{OE}/\overline{OE}$ ).
- Package:
  - EM23C1000AP/BP - 28 pins 600 mil plastic DIP.
  - EM23C1000AM/BM - 28 pins 450 mil plastic SOP.
  - EM23C1000EP/FP - 32 pins 600 mil plastic DIP.

**PIN ASSIGNMENTS**



**BLOCK DIAGRAM**



**FUNCTION DESCRIPTIONS**

EM23C1000A/E

MODE	CE	OE	A0-A16	D0-D7	POWER
READ	ACTIVE	ACTIVE	VALID	DATA OUT	$I_{CC}$
STANDBY	INACTIVE	*	*	HIGH-Z	$I_{SB}$
OUTPUT DISABLE	ACTIVE	INACTIVE	*	HIGH-Z	$I_{CC}$

EM23C1000B/F

MODE	CS1	CS2	A0-A16	D0-D7	POWER
READ	ACTIVE	ACTIVE	VALID	DATA OUT	$I_{CC}$
OUTPUT DISABLE	INACTIVE	*	*	HIGH-Z	$I_{CC}$
OUTPUT DISABLE	*	INACTIVE	*	HIGH-Z	$I_{CC}$

NOTE : “ \* “ MEANS ACTIVE ( VALID ) OR INACTIVE ( INVALID )

**ABSOLUTE MAXIMUM RATINGS**

Items	Sym.	Condition	Rating
Supply voltage	$V_{CC}$		- 0.3V to 7 V
Input voltage	$V_{IN}$		- 0.3V to $V_{CC}+0.3V$
Output voltage	$V_{OUT}$		- 0.3V to $V_{CC}+0.3V$
Operating temperature	$T_{OPR}$		0 to 70°C
Storage temperature	$T_{STR}$		-65°C to 150°C

**RECOMMENDED OPERATING CONDITIONS ( $T_{OPR}=0\sim 70^{\circ}C$ )**

Parameter	Sym.	Min.	Max.	Unit
SUPPLY VOLTAGE	$V_{CC}$	4.5	5.5	V

**DC ELECTRICAL CHARACTERISTICS ( $V_{CC} = 4.5V$  to  $5.5V$ ,  $T_{OPR}=0\sim 70^{\circ}C$ )**

Parameter	Sym.	Condition	Min.	Max.	Unit	Note
Input “Low” voltage	$V_{IL}$		-0.3	0.8	V	
Input “High” voltage	$V_{IH}$		2.2	$V_{CC}+0.3$	V	
Output “Low” voltage	$V_{OL}$	$I_{OL} = 400mA$		0.4	V	
Output “High” voltage	$V_{OH}$	$I_{OH} = -100mA$	2.4		V	
Input leakage current	$I_{LI}$	$V_{IN} = 0V$ to $V_{CC}$		10	$\mu A$	
Output leakage current	$I_{LO}$	$V_{OUT} = 0V$ to $V_{CC}$		10	$\mu A$	1
Operating current	$I_{CC}$	$t_{RC} = 150ns$		35	mA	
Standby current	$I_{SB}$	$CE = V_{IH}$		2	mA	
		$CE = V_{CC} - 0.2V$		30	$\mu A$	2
Input capacitance	$C_{IN}$	$f = 1MHz$ ,		10	pF	
Output capacitance	$C_{OUT}$	$t_A = 25^{\circ}C$		10	pF	

Note:

- $\overline{CE} / \overline{OE} = V_{IH}$ ,  $OE = V_{IL}$ , outputs open
- Automatic power down version

( $V_{CC} = 4.5V$  to  $5.5V$   $T_{OPR} = 0 \sim 70^{\circ}C$ )

Parameter	Sym.	Condition	Min.	Max.	Unit
Cycle time	$t_{CYC}$		150		ns
Address access time	$t_{ACC}$			150	ns
Output hold after address change	$t_{OH}$		10		ns
Chip enable access time	$t_{CE}$	1		150	ns
Chip select access time	$t_{CS}$	3		70	ns
Output enable access time	$t_{OE}$	1,3		70	ns
Output disable delay	$t_{DF}$	2		50	ns

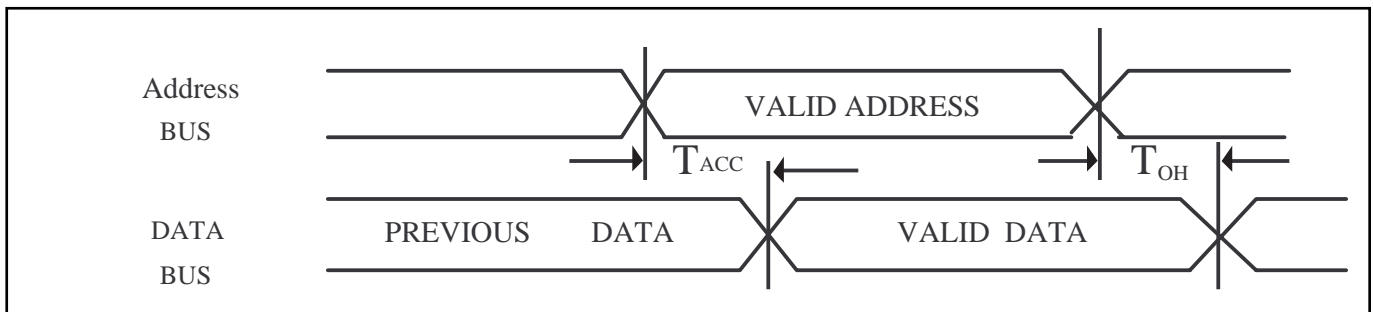
Note: 1. Power down type only. (A/E).

2. Outputs high impedance delay ( $t_{DF}$ ) is measure from either  $\overline{CE}$  or OE going high or CS going inactive, whichever occurs first.

3. Functions of  $\overline{CS}/CS$  &  $\overline{OE}/OE$  are identical.

## TIMING DIAGRAM

Propagation delay from Address ( $\overline{CE}/\overline{CE}$ =Enable or  $\overline{CS}/\overline{CS}$ =Active)



Propagation delay from Chip Enable or Chip Select (Address Valid)

